図面番号(DRAWING NO.) SJ100130

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITTING	E.MURANO	Y.YAHIRO	—	K.Hisatomi

DESIGNATION

MM50−200B＊−＊RE

- SERIES PREFIX シリーズ名
- NO. OF CONTACTS 芯数
- SOCKET TYPE ソケットタイプ B:LATCH TYPE SMT
- KEYING TYPE(DETAIL A) キィタイプ 2:TYPE B(1.8V) 1:TYPE A(2.5V)
- CONTACT FINISH 接点仕上げ 1:Au(0.1μm MIN) OVER NI 2:Au(0.3μm MIN) OVER NI
- R :REVERSE NONE:STANDARD
- 錫または錫合金(無鉛) (LEAD FREE)TIN/TIN ALLOY

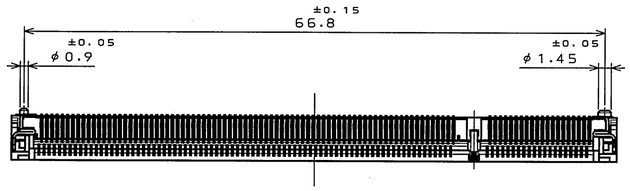
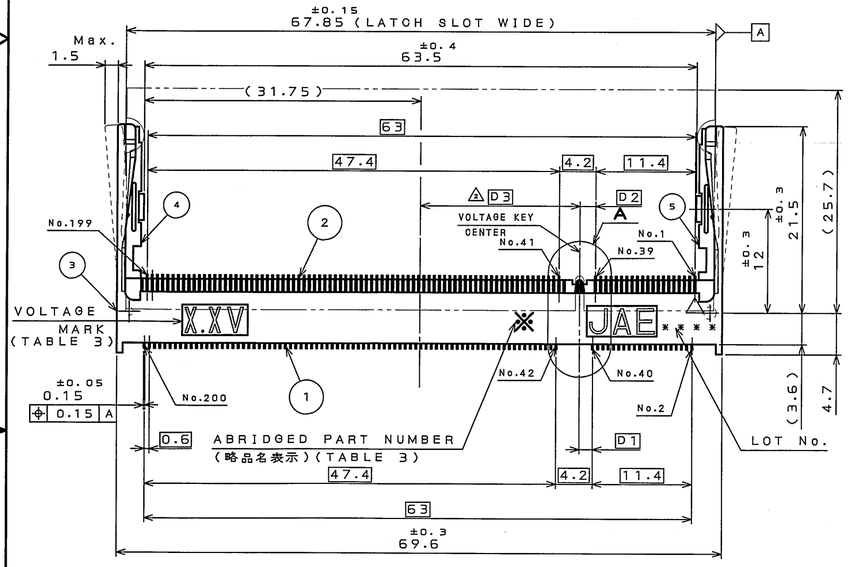
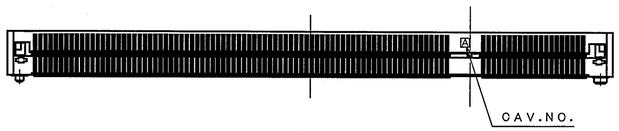


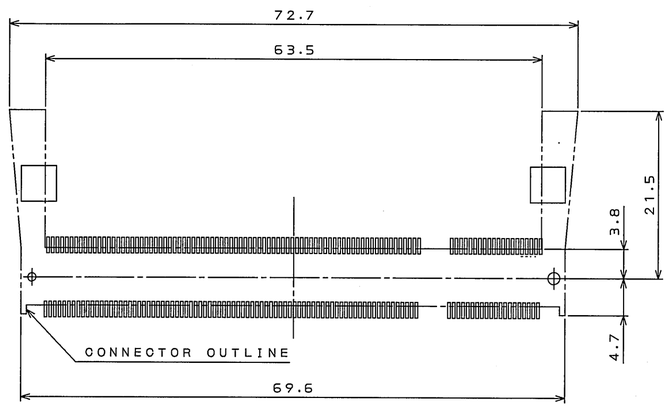
TABLE2

CONTACT FINISH

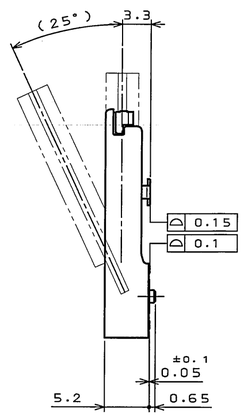
PARTS NAME	CONTACT AREA	SOLDERING AREA
MM50−200B＊−1RE	Au(0.1μm Min.) OVER Ni	GOLD FLASH OVER Ni
MM50−200B＊−2RE	Au(0.3μm Min.) OVER Ni	GOLD FLASH OVER Ni







CONNECTOR MOUNTED AREA(REF.)



DETAIL A
(SCALE 5:1)
(REF.TABLE1)

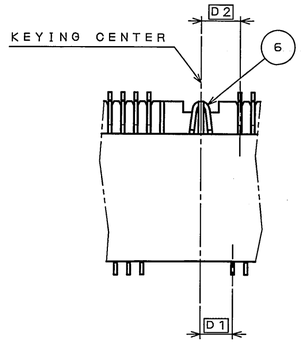
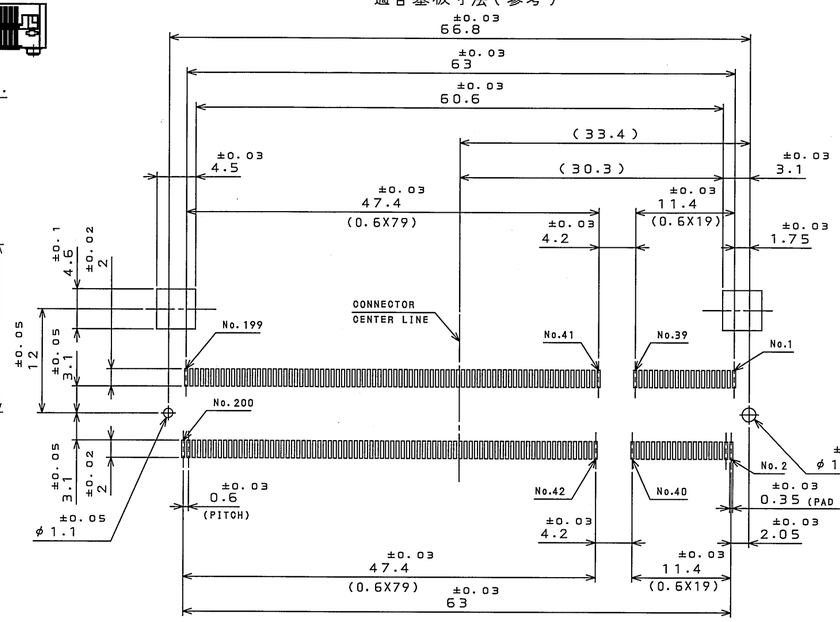


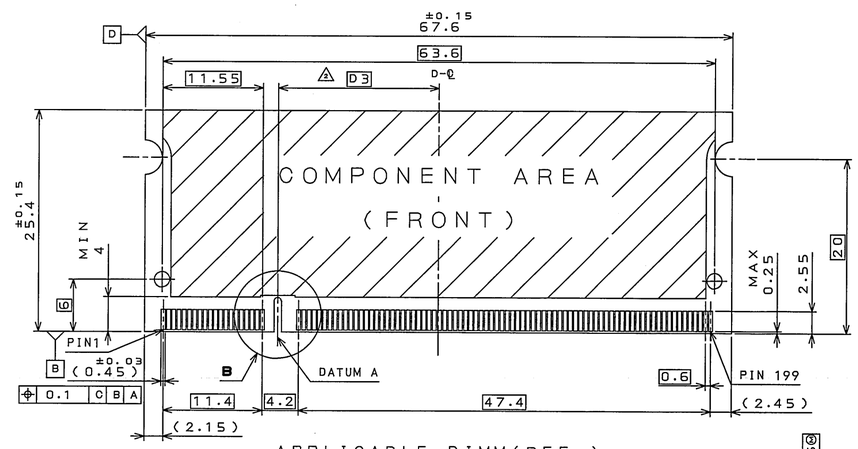
TABLE3

DISCRIMINATION MARK

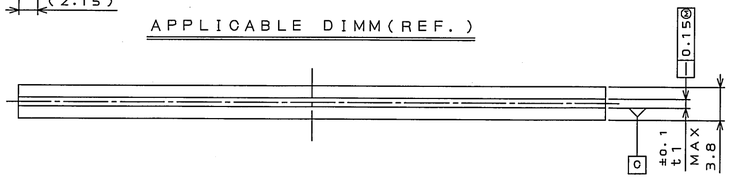
PARTS NAME	VOLTAGE MARK	ABRIDGED PART NUMBER
MM50−200B1−＊RE	2.5V	＊RE
MM50−200B2−＊RE	1.8V	2−＊RE

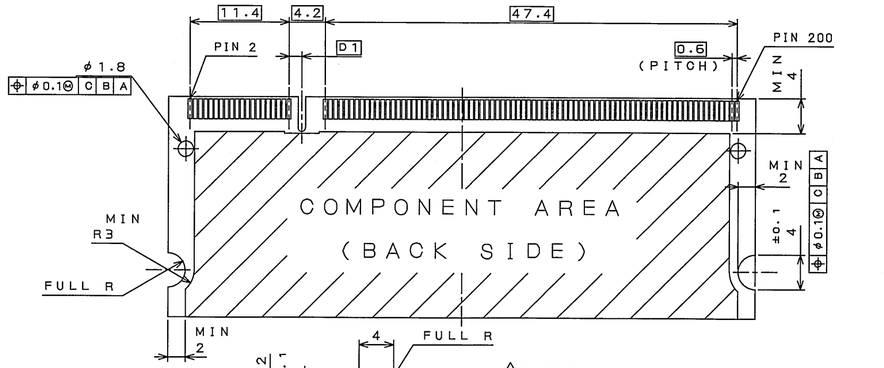
APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

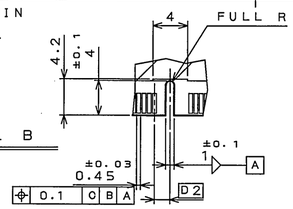




APPLICABLE DIMM(REF.)







DETAIL B

TABLE1

MECHANICAL KEYING

POWER SPPLY	D1	D2	D3
2.5V(TYPE A)	1.5	1.8	18.45
1.8V(TYPE B)	2.4	2.7	17.55

NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
6	KEY	1	STAINLESS	—	—
5	HOLD DOWN 2	1	PHOSPHOR BRONZE	TIN PLATING	—
4	HOLD DOWN 1	1	PHOSPHOR BRONZE	TIN PLATING	—
3	INSULATOR	1	GLASS FILLED LCP	—	UL94 V−0 COLOR WHITE
2	BOTTOM SIDE CONTACT	100	PHOSPHOR BRONZE	SEE TABLE 2	—
1	TOP SIDE CONTACT	100	PHOSPHOR BRONZE	SEE TABLE 2	—

仕様書(SPECIFICATION): JAOS−1655−01

一般公差(GENERAL TOLERANCE)

寸法(DIMENSION)	角度(ANGLES)
. ±0.8	×° ±
.× ±0.4	×°× '±
.×× ±0.1	
.××× ±	

第1版(ORIGINAL DATE): 24.Oct.2003

製図 DR.: —

担当 CHK.: R.KATOU

査閲 APPD.: Y.YAHIRO

承認 APPD.: S.KASHIWAGI

尺度(SCALE): 2:1

シリーズ(SERIES): MM50

名称(TITLE): MM50 −200B＊−＊RE

質量(MASS):

日本航空電子工業株式会社
JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

図面番号(DRAWING NO.): SJ100130

SIZE A2

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